SPT-SMD 1,5/ 2-H-5,08 R24 - PCB terminal block

1824857

https://www.phoenixcontact.com/us/products/1824857

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Printed circuit board terminal, nominal current: 17.5 A, rated voltage (III/2): 320 V, nominal cross section: 1.5 mm^2, number of potentials: 2, number of rows: 1, number of positions per row: 2, product range: SPT 1,5/..-H-SMD, pitch: 5.08 mm, connection method: Push-in spring connection, mounting: SMD soldering, conductor/PCB connection direction: 0 °, color: black, Pin layout: Linear pad geometry, number of solder pins per potential: 1, type of packaging: 24 mm wide tape

Your advantages

- Time saving push-in connection, tools not required
- Defined contact force ensures that contact remains stable over the long term
- Intuitive operation due to color-coded actuating push button
- Designed for integration into the SMT soldering process
- Quick and convenient testing using integrated test option
- Operation and conductor connection from one direction enable integration into front of device
- Anti-rotation pins reduce the mechanical strain on the soldering spots

Commercial data

Item number	1824857
Packing unit	300 pc
Minimum order quantity	300 pc
Note	Made to order (non-returnable)
Sales key	AA12
Product key	AALDAD
Catalog page	Page 9 (NTK-2014)
GTIN	4046356817059
Weight per piece (including packing)	2.33 g
Weight per piece (excluding packing)	2.33 g
Customs tariff number	85369010
Country of origin	PL

Technical data

Product properties

Product type	Printed circuit board terminal
Product family	SPT 1,5/..-H-SMD
Product line	COMBICON Terminals S
Number of positions	2
Pitch	5.08 mm
Number of connections	2
Number of rows	1
Number of potentials	2
Pin layout	Linear pad geometry
Solder pins per potential	1

Data management status

Article revision	05

Electrical properties

Nominal current I_N	17.5 A
Nominal voltage U_N	320 V
Rated voltage (III/3)	250 V
Rated surge voltage (III/3)	4 kV
Rated voltage (III/2)	320 V
Rated surge voltage (III/2)	4 kV
Rated voltage (II/2)	500 V
Rated surge voltage (II/2)	4 kV

Connection data

Connection technology

Nominal cross section	1.5 mm²

Conductor connection

Connection method	Push-in spring connection
Conductor cross section rigid	0.2 mm² ... 1.5 mm²
Conductor cross section flexible	0.2 mm² ... 1.5 mm²
Conductor cross section AWG	24 ... 16
Conductor cross section flexible, with ferrule without plastic sleeve	0.2 mm² ... 1.5 mm²
Conductor cross section, flexible, with ferrule, with plastic sleeve	0.2 mm² ... 0.75 mm²
Stripping length	8 mm

Mounting

Mounting type	SMD soldering
Pin layout	Linear pad geometry

Processing notes

Process	Reflow soldering
Moisture Sensitive Level	MSL 1
Classification temperature T_c	260 °C
Solder cycles in the reflow	3

Material specifications

Material data - contact

Note	WEEE/RoHS-compliant, free of whiskers according to IEC 60068-2-82/JEDEC JESD 201
Contact material	Cu alloy
Surface characteristics	hot-dip tin-plated
Metal surface terminal point (top layer)	Tin (4 - 8 µm Sn)
Metal surface soldering area (top layer)	Tin (4 - 8 µm Sn)

Material data - housing

Color (Housing)	black (9005)
Insulating material	LCP
Insulating material group	IIIa
CTI according to IEC 60112	175
Flammability rating according to UL 94	V0

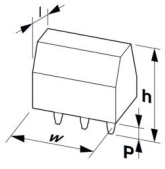
Material data – actuating element

Color (Actuating element)	white (9010)
Insulating material	PA GF
Insulating material group	I
CTI according to IEC 60112	600
Flammability rating according to UL 94	V0

Notes

Notes on operation	The solder anchors on the outer poles reduce the mechanical strain on the SMD soldering spots.
Assembly note	This item is not suitable for PCB cleaning with liquids.

Dimensions

Dimensional drawing	
Pitch	5.08 mm
Width [w]	9.08 mm
Height [h]	9.7 mm
Length [l]	13.6 mm

Installed height	7.7 mm
Pin dimensions	0.7 x 0.3 mm

PCB design

Pad geometry	1.6 x 4 mm
Pin spacing	7 mm
Hole diameter	1.1 mm

Mechanical tests

Connection test

Specification	IEC 60998-2-2:2002-12
Result	Test passed

Test for conductor damage and slackening

Specification	IEC 60998-2-2:2002-12
Result	Test passed

Pull-out test

Specification	IEC 60998-2-2:2002-12
Conductor cross section/conductor type/tractive force setpoint/actual value	0.2 mm² / solid / > 10 N
	0.2 mm² / flexible / > 10 N
	1.5 mm² / solid / > 40 N
	1.5 mm² / flexible / > 40 N

Flexion test

Specification	IEC 60998-2-2:2002-12
Result	Test passed

Electrical tests

Temperature-rise test

Specification	IEC 60947-7-4:2019-01
Requirement temperature-rise test	The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting temperature.

Insulation resistance

Specification	IEC 60998-1:2002-12
Insulation resistance, neighboring positions	> 5 MΩ

Air clearances and creepage distances |

Specification	IEC 60664-1:2007-04
Insulating material group	IIIa
Comparative tracking index (IEC 60112)	CTI 175
Rated insulation voltage (III/3)	250 V
Rated surge voltage (III/3)	4 kV
minimum clearance value - non-homogenous field (III/3)	3 mm
minimum creepage distance (III/3)	4 mm

Rated insulation voltage (III/2)	320 V
Rated surge voltage (III/2)	4 kV
minimum clearance value - non-homogenous field (III/2)	3 mm
minimum creepage distance (III/2)	3.2 mm
Rated insulation voltage (II/2)	500 V
Rated surge voltage (II/2)	4 kV
minimum clearance value - non-homogenous field (II/2)	3 mm
minimum creepage distance (II/2)	5 mm

Environmental and real-life conditions

Vibration test

Specification	IEC 60068-2-6:2007-12
Frequency	10 - 150 - 10 Hz
Sweep speed	1 octave/min
Amplitude	0.35 mm (10 Hz ... 60.1 Hz)
Acceleration	5g (60.1 Hz ... 150 Hz)
Test duration per axis	2.5 h
Test directions	X-, Y- and Z-axis

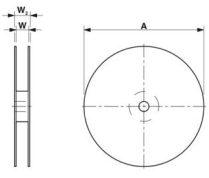
Glow-wire test

Specification	IEC 60998-1:2002-12
Temperature	850 °C
Time of exposure	5 s

Ambient conditions

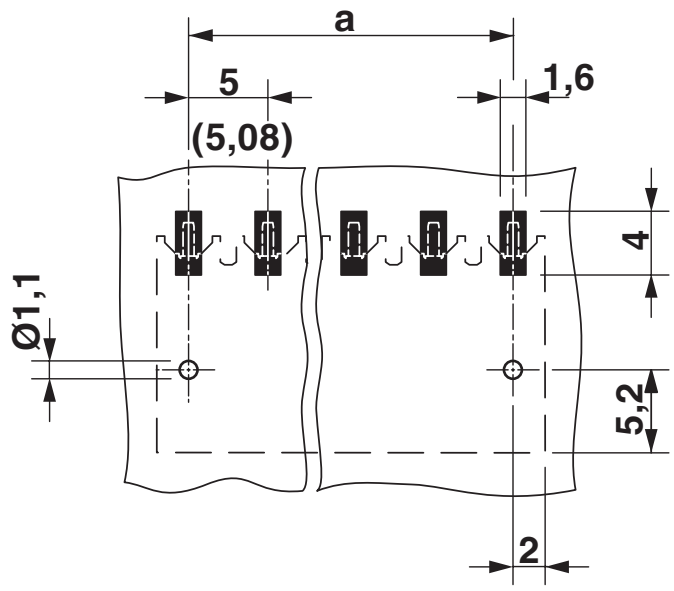
Ambient temperature (operation)	-40 °C ... 105 °C (Depending on the current carrying capacity/derating curve)
Ambient temperature (storage/transport)	-40 °C ... 70 °C
Relative humidity (storage/transport)	30 % ... 70 %
Ambient temperature (assembly)	-5 °C ... 100 °C

Packaging specifications

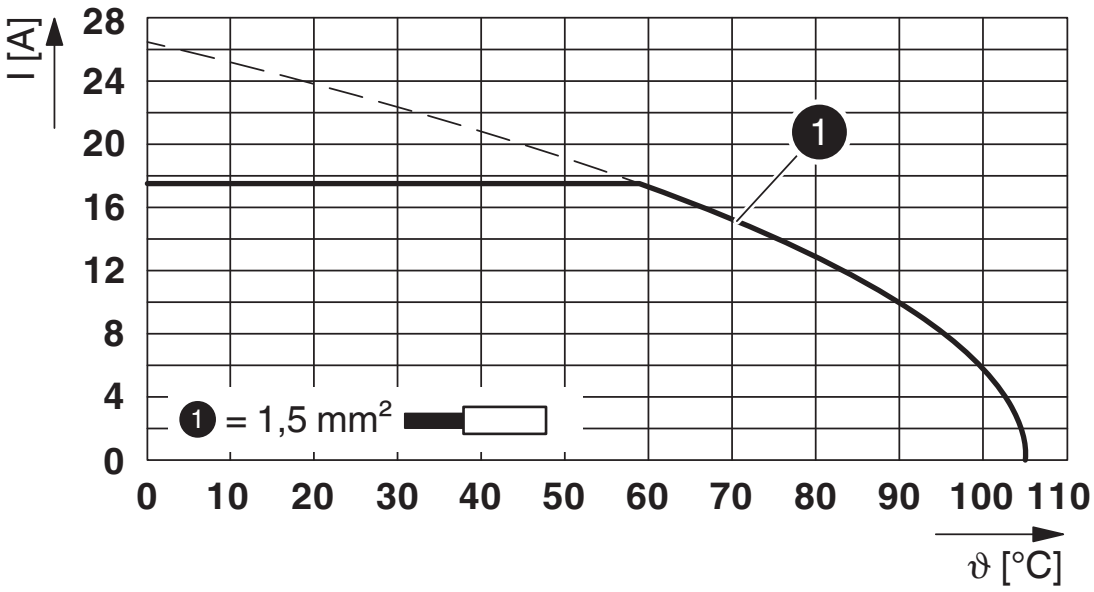
Dimensional drawing	
Type of packaging	24 mm wide tape
[W] tape width	24 mm
[W2] coil overall dimension	30.4 mm
[A] coil diameter	330 mm
Outer packaging type	Transparent-Bag
ESD level	(D) electrostatically conductive
Specification	DIN EN 61340-5-1 (VDE 0300-5-1): 2008-07

Drawings

Drilling plan/solder pad geometry

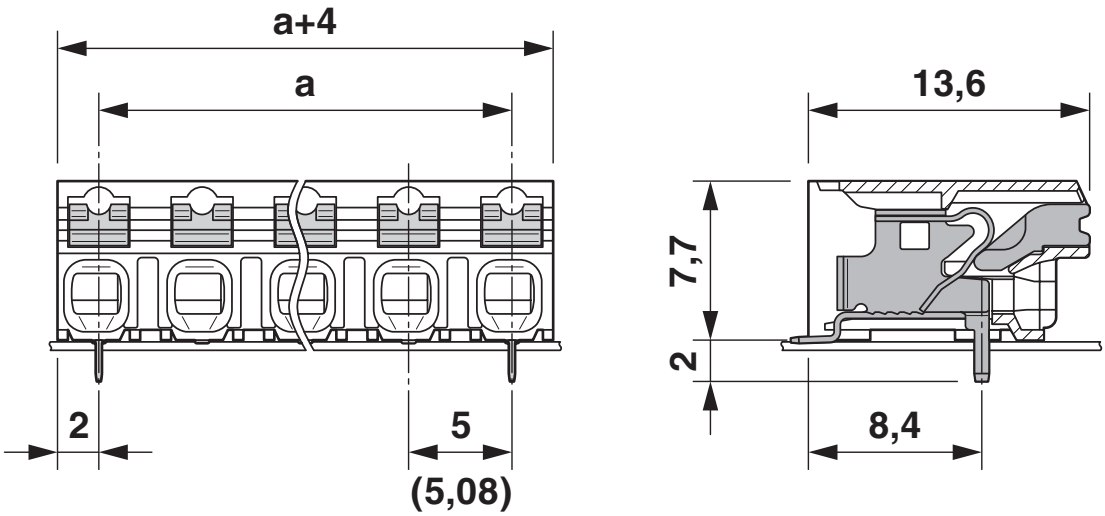


Diagram



Type: SPT-SMD 1,5/...-H-5,08 R...

Dimensional drawing



Approvals

To download certificates, visit the product detail page: https://www.phoenixcontact.com/us/products/1824857

cULus Recognized
Approval ID: E60425-20061129

	Nominal voltage U_N	Nominal current I_N	Cross section AWG	Cross section mm^2
Use group B				
	300 V	10 A	24 - 16	-
Use group D				
	300 V	10 A	24 - 16	-

VDE Zeichengenehmigung
Approval ID: 40046113

	Nominal voltage U_N	Nominal current I_N	Cross section AWG	Cross section mm^2
	320 V	17.5 A	-	0.2 - 1.5

Classifications

ECLASS

ECLASS-11.0	27460101
ECLASS-12.0	27460101
ECLASS-13.0	27460101

ETIM

ETIM 9.0	EC002643

UNSPSC

UNSPSC 21.0	39121400

Environmental product compliance

EU RoHS

Fulfills EU RoHS substance requirements	Yes, No exemptions

China RoHS

Environment friendly use period (EFUP)	EFUP-E
	No hazardous substances above the limits

EU REACH SVHC

REACH candidate substance (CAS No.)	No substance above 0.1 wt%

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